These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

After verifying lens of A1 is clean and undistorted, snap cover H9 over sensor A1 during final hardware assembly.
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